

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Alcoe *et al.*

Art Unit:

Serial No.:

Dkt. No.: END920010111US2

Filed:

Examiner:

Title: **MODULE WITH ADHESIVELY ATTACHED HEAT SINK**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Preliminary Amendment

Sir:

Kindly enter this amendment prior to initial examination

In the Specification:

Page 1, between lines 1 and 2, insert: --This application is a divisional of Serial No. 10/058,999; filed on 1/29/2002.--

Please amend the paragraphs beginning on page 1, line 13 and ending on page 2, line 20 as follows:

The present invention provides an electronic structure, comprising:

- a substrate;
- a semiconductor device electrically coupled to the substrate;
- a stiffener ring adhesively coupled to the substrate, wherein the stiffener ring surrounds the semiconductor; and
- a cover plate on a top surface of the semiconductor and on a top surface of the stiffener